Ablestik

Silver Plated Copper (SPC)

Die Attach Technology

Silver is one of the major cost drivers in conductive die attach. Over the last 10 years the electronics industry has seen silver prices more than tripled making it difficult for the semiconductor packing companies to control their raw material costs. The roll out of Henkel's new silver plated copper (SPC) die attach filler technology is one way to control cost without compromising performance by reducing metal content. This innovative filler technology combined with Henkel's new resin platform is a tool semiconductor packaging companies can use to help hedge against silver prices.

Henkel

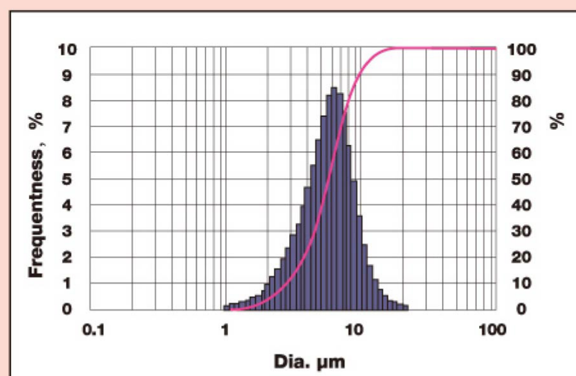
Silver Plated Copper (SPC)

Technical Achievements	
Volume Resistance	1*10E-04 ohm-cm
Thermal Conductivity	> 3 W/mK
Work Life	> 24hrs
Particle Size	< 20 µm
Dispensing Ability	Excellent
Reliability	Excellent

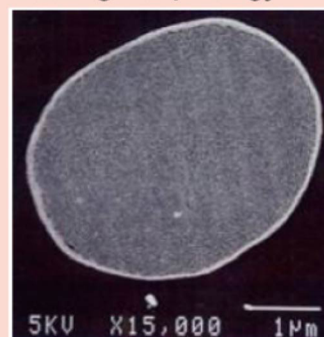
A view on SPC filler

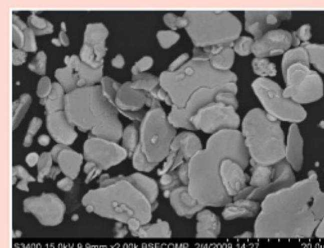
Particle size distribution

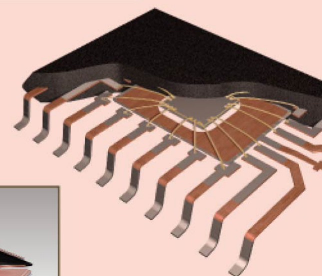
PSD	D90	9.6 µm
	D50	5.8 µm
	D10	2.9 µm
S.S.A		0.30 m^3/g
Tap Density		3.8 g/cm^3
Ag Content		10.7 wt%

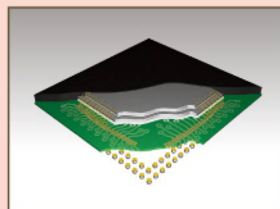
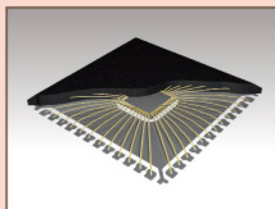
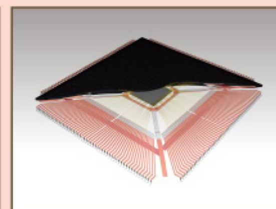


Coating morphology







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